

CASCADABLE BROADBAND GaAs MMIC AMPLIFIER DC TO 10GHz

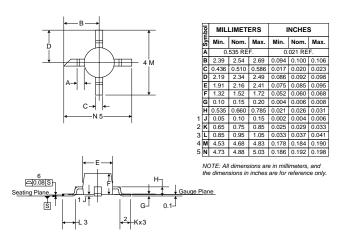
Typical Applications

- Narrow and Broadband Commercial and Military Radio Designs
- Linear and Saturated Amplifiers

Product Description

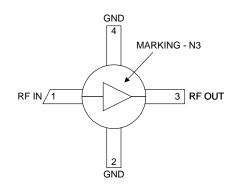
The NLB-300 cascadable broadband InGaP/GaAs MMIC amplifier is a low-cost, high-performance solution for general purpose RF and microwave amplification needs. This 50 Ω gain block is based on a reliable HBT proprietary MMIC design, providing unsurpassed performance for small-signal applications. Designed with an external bias resistor, the NLB-300 provides flexibility and stability. The NLB-300 is packaged in a low-cost, surface-mount plastic package, providing ease of assembly for high-volume tape-and-reel requirements.

 Gain Stage or Driver Amplifiers for MWRadio/Optical Designs (PTP/PMP/ LMDS/UNII/VSAT/WLAN/Cellular/DWDM)



Optimum Technology Matching® Applied

-	•••	
🗌 Si BJT	🗌 GaAs HBT	GaAs MESFET
Si Bi-CMOS	SiGe HBT	Si CMOS
InGaP/HBT	🗌 GaN HEMT	SiGe Bi-CMOS



Functional Block Diagram

Package Style: Micro-X, 4-Pin, Plastic

Features

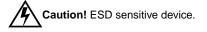
- Reliable, Low-Cost HBT Design
- 13.0dB Gain, +11.1dBm P1dB@2GHz
- High P1dB of +14.1dBm@6.0GHz and +12.7dBm@10.0GHz
- Single Power Supply Operation
- 50 Ω I/O Matched for High Freq. Use

Ordering Information

NLB-300	Cascadable Broadband Ga 10GHz	As MMIC Amplifier DC to
NLB-300-T1 or -T	3Tape & Reel, 1000 or 3000	Pieces (respectively)
NLB-300-E	Fully Assembled Evaluation	Board
NBB-X-K1 RF Micro Devices, 7628 Thorndike Rc Greensboro, NC 27	ad	P Amp Designer's Tool Kit Tel (336) 664 1233 Fax (336) 664 0454 http://www.rfmd.com

Absolute Maximum Ratings

Parameter	Rating	Unit
RF Input Power	+20	dBm
Power Dissipation	300	mW
Device Current	70	mA
Channel Temperature	200	°C
Operating Temperature	-45 to +85	°C
Storage Temperature	-65 to +150	°C
E P	C (1	4 1



RF Micro Devices believes the furnished information is correct and accurate at the time of this printing. However, RF Micro Devices reserves the right to make changes to its products without notice. RF Micro Devices does not assume responsibility for the use of the described product(s).

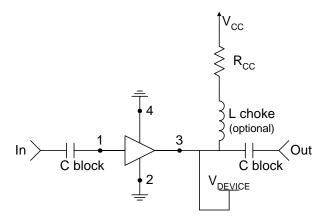
Exceeding any one or a combination of these limits may cause permanent damage.

Deremeter	Specification			11	Condition	
Parameter	Min. Typ.		Max. Unit		Condition	
Overall					V _D =+3.8V, I _{CC} =50mA, Z ₀ =50Ω, T _A =+25°C	
Small Signal Power Gain, S21	12.0	13.0		dB	f=0.1GHz to 1.0GHz	
_		10.7		dB	f=1.0GHz to 4.0GHz	
		8.9		dB	f=4.0GHz to 6.0GHz	
	8.5	8.9		dB	f=6.0GHz to 10.0GHz	
		8.5		dB	f=10.0GHz to 12.0GHz	
Gain Flatness, GF		±0.1		dB	f=5.0GHz to 10.0GHz	
Input VSWR		2.2:1			f=0.1GHz to 4.0GHz	
		2.8:1			f=4.0GHz to 7.0GHz	
		2.0:1			f=7.0GHz to 12.0GHz	
Output VSWR		2.2:1			f=0.1GHz to 4.0GHz	
		2.9:1			f=4.0GHz to 7.0GHz	
		2.4:1			f=7.0GHz to 12.0GHz	
Output Power @						
-1dB Compression, P1dB		11.1		dBm	f=2.0GHz	
		14.1		dBm	f=6.0GHz	
		12.7		dBm	f=10.0GHz	
Noise Figure, NF		4.9		dB	f=3.0GHz	
Third Order Intercept, IP3		+28.6		dBm	f=2.0GHz	
		+27.0			f=6.0GHz	
Reverse Isolation, S12		-16		dB	f=0.1GHz to 20.0GHz	
Device Voltage, V _D	3.6	3.8	4.2	V		
Gain Temperature Coefficient, δG _T /δT		-0.0015		dB/°C		
MTTF versus Temperature						
@ I _{CC} =50mA						
Case Temperature		85		°C		
Junction Temperature		113		°C		
MTTF		>1,000,000		hours		
Thermal Resistance						
θ ^{JC}		147		°C/W	$\frac{J_T - T_{CASE}}{V_D \cdot I_{CC}} = \theta_{JC}(°C/Watt)$	

Pin	Function	Description	Interface Schematic
1	RF IN	RF input pin. This pin is NOT internally DC-blocked. A DC-blocking capacitor, suitable for the frequency of operation, should be used in most applications. DC coupling of the input is not allowed, because this will override the internal feedback loop and cause temperature instability.	
2	GND	Ground connection. For best performance, keep traces physically short and connect immediately to ground plane.	
3	RF OUT	RF output and bias pin. Biasing is accomplished with an external series resistor and choke inductor to V _{CC} . The resistor is selected to set the DC current into this pin to a desired level. The resistor value is determined by the following equation: $R = \frac{(V_{CC} - V_{DEVICE})}{I_{CC}}$ Care should also be taken in the resistor selection to ensure that the current into the part never exceeds maximum datasheet operating current over the planned operating temperature. This means that a resistor between the supply and this pin is always required, even if a supply near 5.0V is available, to provide DC feedback to prevent thermal runaway. Because DC is present on this pin, a DC-blocking capacitor, suitable for the frequency of operation, should be used in most applications. The supply side of the bias network should also be well bypassed.	RF IN O
4	GND	Same as pin 2.	

Typical Bias Configuration

Application notes related to biasing circuit, device footprint, and thermal considerations are available on request.

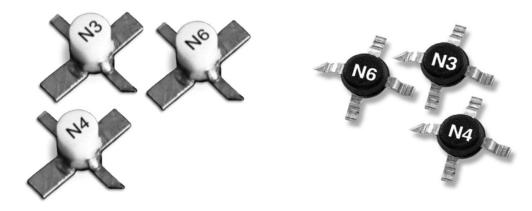


Recommended Bias Resistor Values						
Supply Voltage, V _{CC} (V)	5	8	10	12	15	20
Bias Resistor, R_{CC} (Ω)	22	82	122	162	222	322

Extended Frequency InGaP Amplifier Designer's Tool Kit NBB-X-K1

This tool kit was created to assist in the design-in of the RFMD NBB- and NLB-series InGap HBT gain block amplifiers. Each tool kit contains the following.

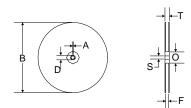
- 5 each NBB-300, NBB-310 and NBB-400 Ceramic Micro-X Amplifiers
- 5 each NLB-300, NLB-310 and NLB-400 Plastic Micro-X Amplifiers
- 2 Broadband Evaluation Boards and High Frequency SMA Connectors
- Broadband Bias Instructions and Specification Summary Index for ease of operation



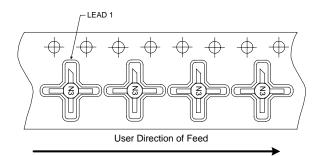
NLB-300

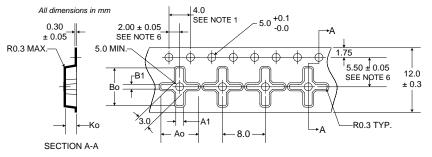
Tape and Reel Dimensions

All Dimensions in Millimeters



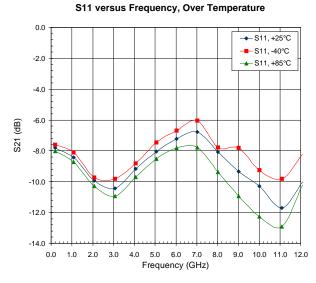
14.732 mm (7") REEL			Plastic, Micro-X		
	ITEMS	SYMBOL	SIZE (mm)	SIZE (inches)	
	Diameter	В	178 +0.25/-4.0	7.0 +0.079/-0.158	
FLANGE	Thickness	Т	18.4 MAX	0.724 MAX	
	Space Between Flange	F	12.8 +2.0	0.50 +0.08	
	Outer Diameter	0	76.2 REF	3.0 REF	
нив	Spindle Hole Diameter	S	13.716 +0.5/-0.2	0.540 +0.020/-0.008	
пов	Key Slit Width	A	1.5 MIN	0.059 MIN	
	Key Slit Diameter	D	20.2 MIN	0.795 MIN	



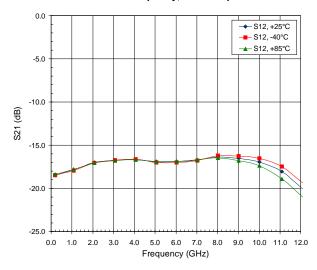


NOTES

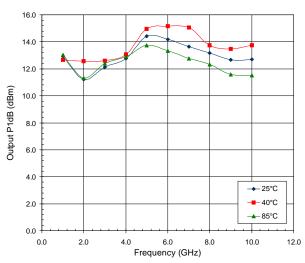
NOTES:	Ao = 7.0 MM
 10 sprocket hole pitch cumulative tolerance ±0.2. 	A1 = 1.8 MM
Camber not to exceed 1 mm in 100 mm.	Bo = 7.0 MM
3. Material: PS+C.	
Ao and Bo measured on a plane 0.3 mm above the bottom of the pocket.	B1 = 1.3 MM
5. Ko measured from a plane on the inside bottom of the pocket to the surface of t	the carrier. Ko = 2.1 MM
6. Pocket position relative to sprocket hole measured as true position of pocket, no	

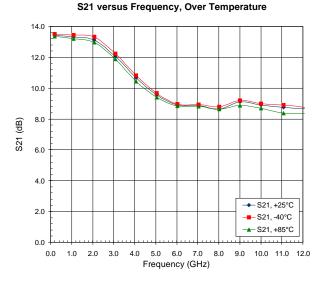


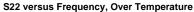
S12 versus Frequency, Over Temperature

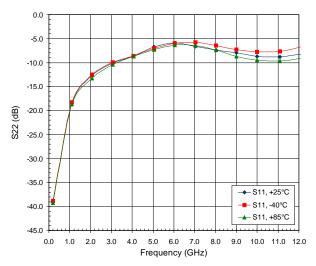


Output P1dB versus Frequency Across Temperature

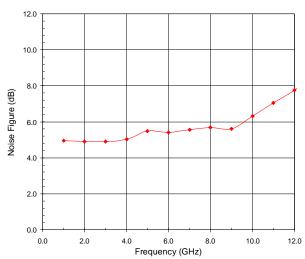












Note: The s-parameter gain results shown include device performance as well as evaluation board and connector loss variations. The insertion losses of the evaluation board and connectors are as follows:

1GHz to 4GHz=-0.06dB 5GHz to 9GHz=-0.22dB 10GHz to 14GHz=-0.50dB 15GHz to 20GHz=-1.08dB